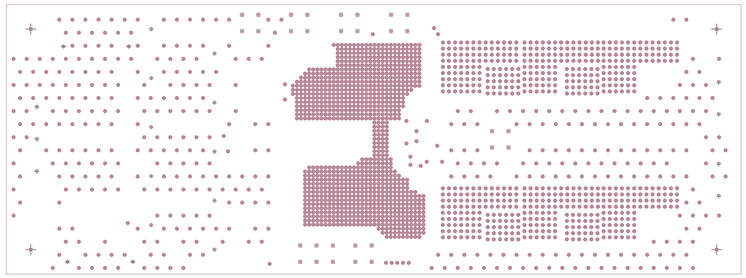
Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	Solder Resist	0.020mm	3.5	
1	L1_Top	Copper	0.070mm		
	Dielectric1	FR-4	1.400mm	4.2	
2	L2_Bot	Copper	0.070mm		
	Bottom Solder	Solder Resist	0.020mm	3.5	
	Bottom Overlay				
Total board thickness:			1.580mm		



Symbol	Count	Hole Size	Plated	Hole Type	Drill Layer Pair	Via/Pad	Pad Shape	Template	Description	Hole Tolerance (+)	Hole Tolerance (-)
✡	4	49.21mil (1.250mm)	PTH	Round	L1_Top - L2_Bot	Pad	Rounded	c185h125			
⌘	4	128.00mil (3.251mm)	NPTH	Round	L1_Top - L2_Bot	Pad	Rounded	c660hn325			
▽	7	51.18mil (1.300mm)	PTH	Round	L1_Top - L2_Bot	Pad	(Mixed)	(Mixed)			
○	10	39.37mil (1.000mm)	PTH	Round	L1_Top - L2_Bot	Pad	Rounded	c190h100			
□	30	43.31mil (1.100mm)	PTH	Round	L1_Top - L2_Bot	Pad	(Mixed)	(Mixed)			
✣	2042	11.81mil (0.300mm)	PTH	Round	L1_Top - L2_Bot	Via	Rounded	v60h30m0mx0			
	2097 Total										

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ENGINEER:		TITLE: TLD2252-2_RCL_EVAL	
PCB DESIGNER: Nita Valentin			
DATE: 22/7/2020	PART NO.:	REL: REL	REV: V1.0
SVN REVISION: Not In VersionControl	FILE NAME: TLD2252-2_RCL_EVAL.PcbDoc	APRV: Makantasi Vasiliki	SCALE: 1:1

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